



PRINTED CIRCUIT BOARDS
INTERCONNECTION CARRIERS

State of the Art: PCB's

Revisio

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01

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Schematic Key for Multilayer and HDI-Technology Build-Ups

a	b	c	d	e	f	g + h + i
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03 107 FR4 35 L41.35 P10_18 s1

columns and equal kind of positions are separated by "_". Equal prefixes in one column are reduced to one.

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Layers	in μ	Material	Build-Up	Assembly	
Layer-1	35 μ	Copper		A1 B	
	100 μ	Prepreg			
	180 μ	Prepreg			
Layer-2	35 μ	Copper			
	410 μ	L-FR4			
	180 μ	Prepreg			
Layer-99	100 μ	Prepreg			
	35 μ	Copper			

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